## RELIABILITY FAILURE RATE SUMMARY

**Search Results**

| | Early Life Failure Rate | MTBF / FIT | | Early Life Failure Rate Supporting Data | | | | MTBF / FIT Supporting Data | | | | | | |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| PR_Tech: | ELFR-DPPM | MTBF | FIT | Confidence Level (%) | Test Temp. (°C) | Sample Size | Number of Failures | Usage Temp. (°C) | Confidence Level (%) | Activation Energy (eV) | Test Temp. (°C) | Test Duration (hrs) | Sample Size | Number of Failures |
| CSD95372A/BQ5M in FET_NCH_LV_Gen2.1 | - | 3.45E+08 | 2.9 | - | - | - | - | 55 | 60 | 0.7 | 125 | 1000 | 8259 | 0 |

[1] Assuming an ambient temperature of 55°C
[2] Chi-squared 60% estimations used to calculate the failure rate
[3] Equivalent unit hours (EUH)
[4] Thermal acceleration factor is calculated from the Arrhenius equation

$$AF = exp\ [(Ea/k) \times (1/Tu - 1/Ta)]$$

where:
AF = acceleration factor
Ea = apparent activation energy in electron volts (eV)
K = Boltzmann's constant ($8.617 \times 10^{-5}$ electron volts/°Kelvin)
Tu = junction temperature at normal use conditions in degrees Kelvin
Ta = junction temperature at accelerated conditions in degrees Kelvin